SEM AND TEM ANALYSIS USING IMAGE J

Rihana Banu
Department of Physics, Govt. First Grade College, Yelahanka Bangalore-64, Karnataka

Abstract: **This report presents the structural and morphological analysis of the synthesized materials using Scanning Electron Microscopy (SEM) and Transmission Electron Microscopy (TEM). SEM was employed to examine the surface topology, grain size, and morphology, revealing detailed insights into the sample's microstructure. TEM provided high-resolution images and diffraction patterns, enabling the investigation of internal structures, crystallinity, and lattice defects at the nanoscale. The combined SEM and TEM analyses offer a comprehensive understanding of the material characteristics, which are critical for correlating microstructural features with functional properties.**

Key words: SEM, TEM, Image J

INTRODUCTION

Scanning Electron Microscopy is a powerful imaging technique used to examine the surface morphology and microstructure of materials at high magnifications. SEM operates by scanning a focused beam of electrons across a specimen's surface, which generates various signals (such as secondary electrons and backscattered electrons) that are collected to form detailed images. SEM provides insights into particle size, shape, texture, and surface features. It is widely used in materials science, nanotechnology, and failure analysis due to its high resolution and depth of field.

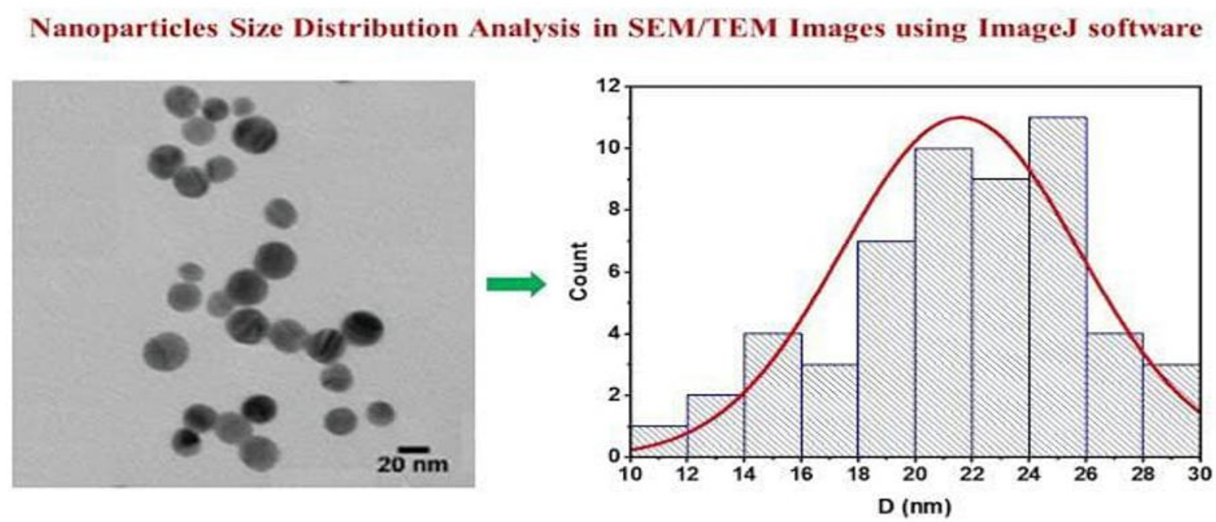
Transmission Electron Microscopy is an advanced technique that allows for imaging at the atomic or nanometre scale. In TEM, a beam of electrons is transmitted through an ultrathin sample, and the interaction of the electrons with the material is used to produce high-resolution images and diffraction patterns. TEM can reveal internal structures, crystallography, defects, and interfaces at a much finer scale than SEM. It is especially valuable for characterizing nanoparticles, thin films, and complex materials in both two-dimensional and diffraction modes.

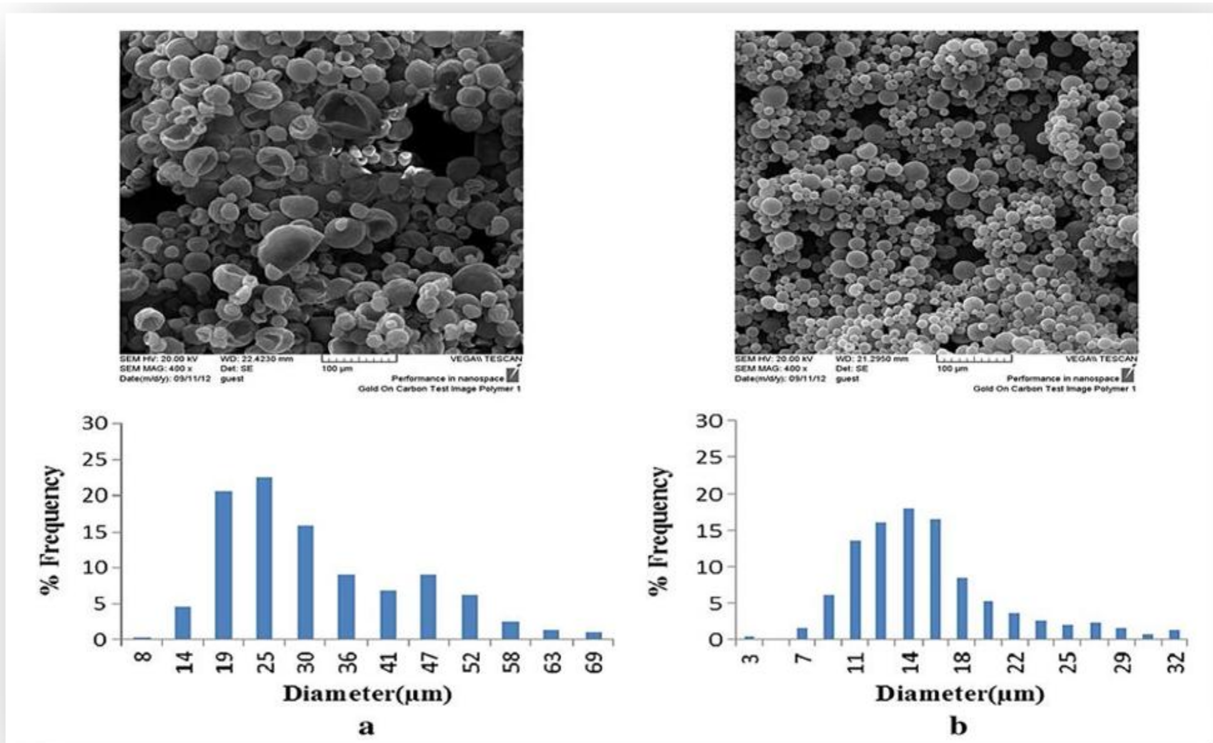
SEM AND TEM ANALYSIS USING J

Scanning Electron Microscopy (SEM) and Transmission Electron Microscopy (TEM) were employed to investigate the surface morphology, particle size, and structural features of the synthesized material. SEM provides detailed topographical and compositional information, while TEM offers high-resolution insights into internal microstructure, crystallinity, and lattice defects.

SEM analysis was performed using a [mention model and manufacturer, e.g., ZEISS EVO 18] operating at an accelerating voltage of [e.g., 10–20 kV]. The images revealed surface texture, grain boundaries, and particle distribution. ImageJ software was used to analyze the SEM micrographs for particle size distribution. The images were converted to grayscale, thresholded, and analyzed using the "Analyze Particles" function to estimate average particle size and distribution histogram.

TEM analysis was carried out using a [mention model and manufacturer, e.g., JEOL JEM-2100] at an accelerating voltage of [e.g., 200 kV]. High-resolution TEM (HRTEM) images revealed fine structural details such as lattice fringes and crystallite boundaries. Selected Area Electron Diffraction (SAED) patterns were also obtained to assess the crystalline nature of the material. ImageJ was used to measure interplanar spacing (d-spacing) by analyzing the HRTEM images and SAED rings, aiding in phase identification and confirmation of XRD results.





PRINCIPLES

1. Scanning Electron Microscopy (SEM):

- Operating Principle: SEM employs a focused electron beam that scans the specimen's surface, producing various signals such as secondary electrons (SE) and backscattered electrons (BSE) to form detailed images.
- Image Formation: Secondary electrons provide topographical contrast, while backscattered electrons offer compositional information based on atomic number differences.
- Resolution and Depth of Field: SEM achieves resolutions below 1 nm with a significant depth of field, rendering three-dimensional-like images of surfaces.

2. Transmission Electron Microscopy (TEM):

- Operating Principle: TEM transmits a high-energy electron beam through an ultra-thin specimen, with the transmitted electrons forming an image that reveals internal structures at atomic resolution.
- Image Formation: Contrast arises from electron scattering due to variations in specimen thickness and composition.
- Resolution Capabilities: Modern TEMs, especially those with aberration correction, can achieve resolutions below 0.5 Å, allowing visualization of individual atoms.

INSTRUMENTATION AND COMPONENTS

1. SEM Components:
   - Electron Gun: Generates the primary electron beam, commonly using thermionic or field emission sources
   - Electromagnetic Lenses: Focus and direct the electron beam onto the specimen.
   - Detectors: Capture signals such as SE and BSE; the Everhart–Thornley detector is widely used for SE detection.
   - Vacuum System: Maintains a high vacuum to prevent electron scattering by air molecules.
2. TEM Components:

- Electron Gun: Produces a coherent electron beam, often utilizing thermionic emission sources like tungsten filaments.
- Condenser and Objective Lenses: Focus the electron beam and form the initial image.
- Imaging System: Includes intermediate and projector lenses, along with detectors such as CCD cameras or direct electron detectors.
- Vacuum System: Essential for minimizing electron scattering and ensuring beam coherence.

SAMPLE PREPARATION TECHNIQUES

1. SEM Sample Preparation:

- Conductive Coating: Non-conductive specimens are coated with thin layers of conductive materials (e.g., gold, platinum) to prevent charging and enhance image quality.
- Mounting: Specimens are affixed to stubs using conductive adhesives to ensure stability and electrical continuity.
- Dehydration and Drying: Biological samples undergo dehydration and critical point drying to preserve structural integrity.

2. TEM Sample Preparation:

- Ultramicrotomy: Specimens are sectioned into ultra-thin slices (<100 nm) using diamond knives.
- Ion Milling: Utilizes ion beams to thin specimens to electron transparency.
- Chemical Etching: Selective removal of material to achieve desired thickness.
- Cryo-Preparation: For sensitive biological samples, cryo-fixation preserves native structures

APPLICATIONS

1. SEM Applications:

- Surface Topography: Analyzing surface features of metals, semiconductors, and polymers.
- Material Characterization: Assessing grain structures, fractures, and corrosion patterns.
- Nanotechnology: Investigating nanostructures and thin films.
- Forensic Analysis: Examining trace evidence and failure analysis.

2. TEM Applications:

- Crystallography: Determining crystal structures and defects.
- Nanomaterials: Characterizing nanoparticles, nanotubes, and quantum dots.
- Phase Identification: Analyzing phase transformations in alloys.
- Interface Studies: Investigating grain boundaries and interfacial phenomena

ADVANCED TECHNIQUES AND DEVELOPMENTS

1. SEM Enhancements:

- Electron Backscatter Diffraction (EBSD): Provides crystallographic information by analysing Kikuchi patterns.
- Energy-Dispersive X-ray Spectroscopy (EDS): Enables elemental analysis and mapping.

- Machine Learning Integration: Automated defect detection and image analysis using AI algorithms.

2. TEM Innovations:

- Aberration Correction: Enhances resolution by correcting lens imperfections.
- Electron Energy Loss Spectroscopy (EELS): Provides information on electronic structure and chemical composition.
- 4D STEM: Combines scanning TEM with diffraction patterns for comprehensive material analysis.

COMPARISION ANALYSIS

SEM VS TEM

FEATURE	SEM	TEM
RESOLUTION	1 nm	<0.1 nm
IMAGE TYPE	Surface topology	Internal structures
SAMPLE THICKNESS	Bulk specimens	Ultra-thin sections (<100 nm)
PREPARATION COMPLEXITY	Moderate	High
APPLICATIONS	Surface analysis, morphology	Crystallography, defect, analysis

LIMITATIONS AND CHALLENGES

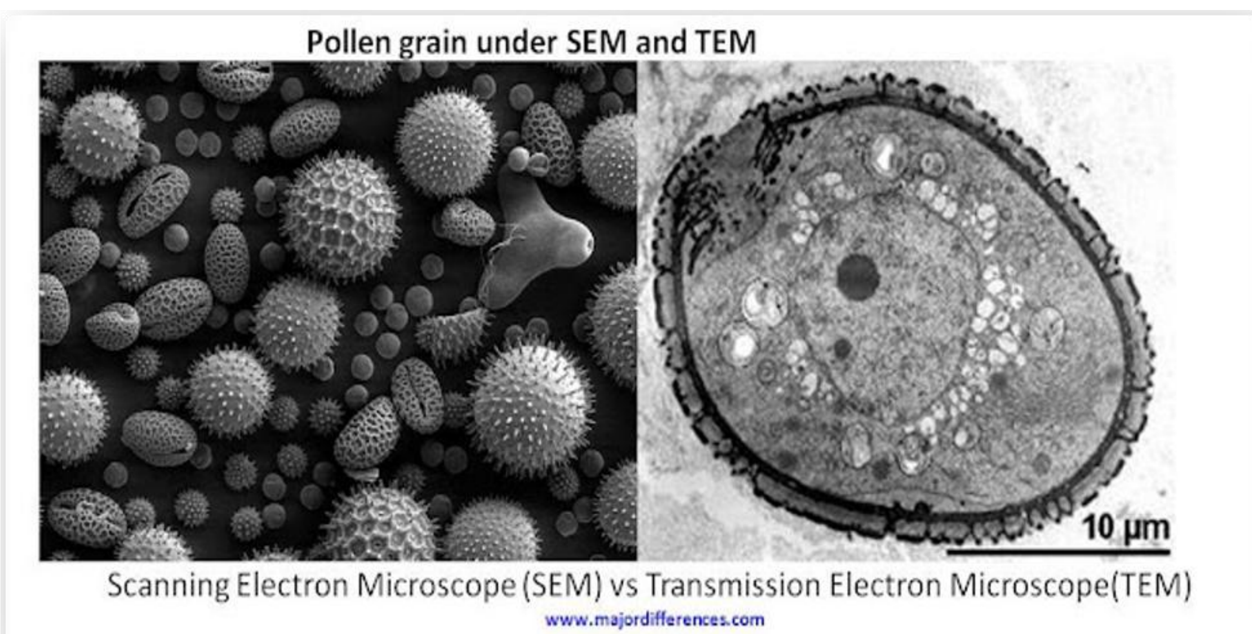
1. SEM:

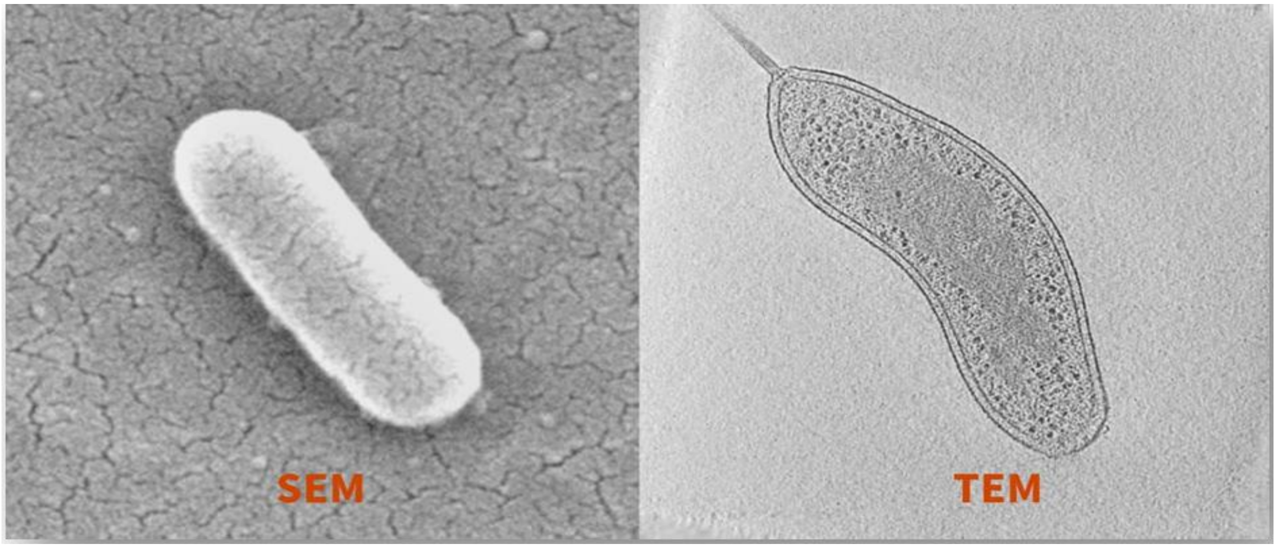
- Charging Effects: Non-conductive samples may accumulate charge, distorting images.
- Surface Sensitivity: Limited to surface or near-surface features.
- Sample Damage: High-energy beams can alter sensitive specimens.

2. TEM:

- Sample Preparation: Requires meticulous thinning, which can introduce artifacts.
- Beam Damage: Prolonged exposure can damage specimens, especially biological materials.
- Field of View: Limited to small areas, potentially missing heterogeneities.

DIAGRAMS





CONCLUSIONS

morphological and microstructural analysis using Scanning Electron Microscopy (SEM) and Transmission Electron Microscopy (TEM) revealed detailed surface features, particle sizes, and crystallinity at the nanoscale. These characterizations collectively validate the quality and functional properties of the synthesized materials, establishing a strong foundation for their use in diverse technological applications such as sensors, photocatalysis, and luminescent devices.

REFERENCES

[1] Goldstein, J., Newbury, D., Joy, D., et al. (2017). Scanning Electron Microscopy and X-ray Microanalysis (4th ed.). Springer. (For SEM techniques)

[2] Williams, D. B., & Carter, C. B. (2009). Transmission Electron Microscopy: A Textbook for Materials Science (2nd ed.). Springer (For TEM fundamentals]